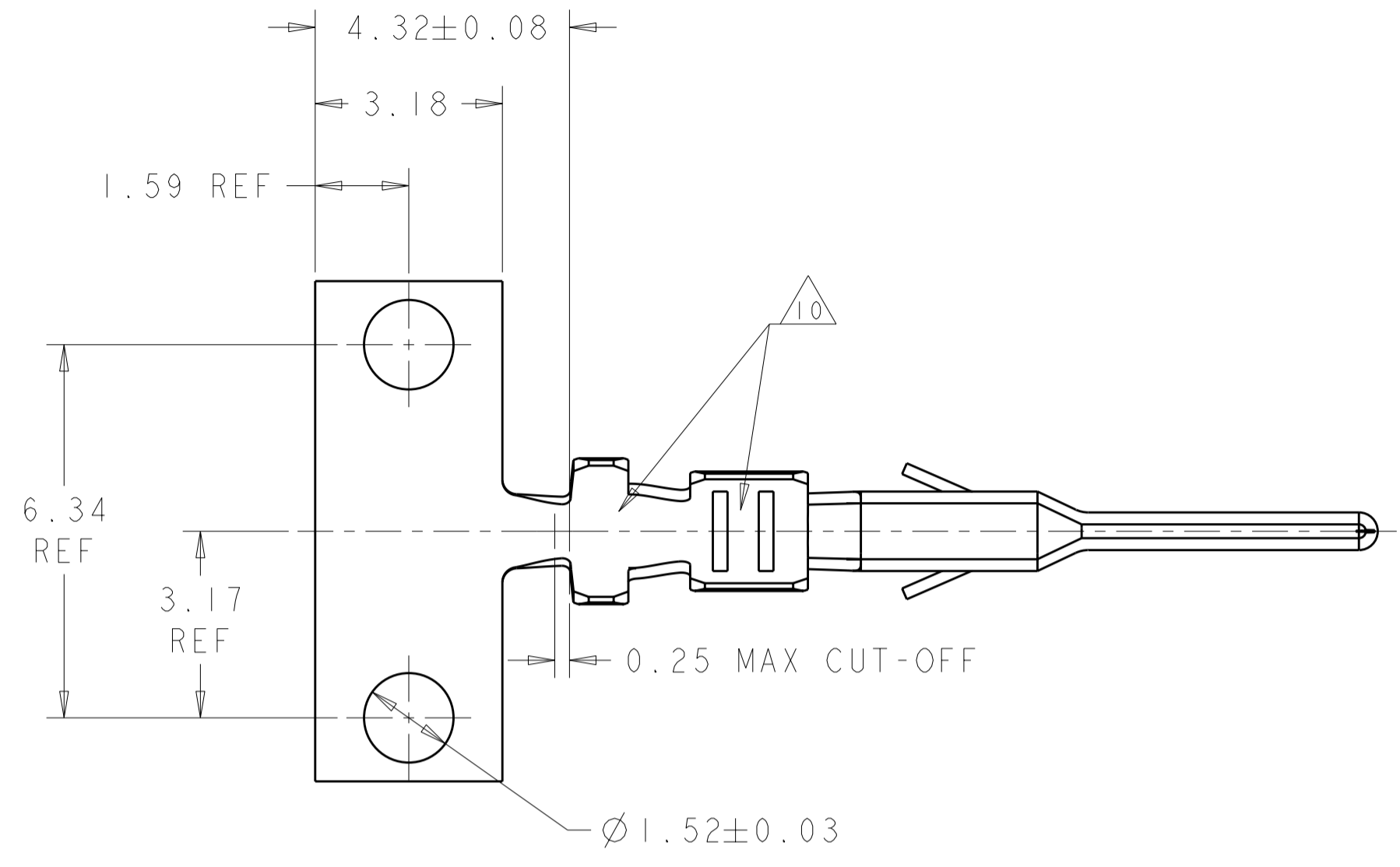
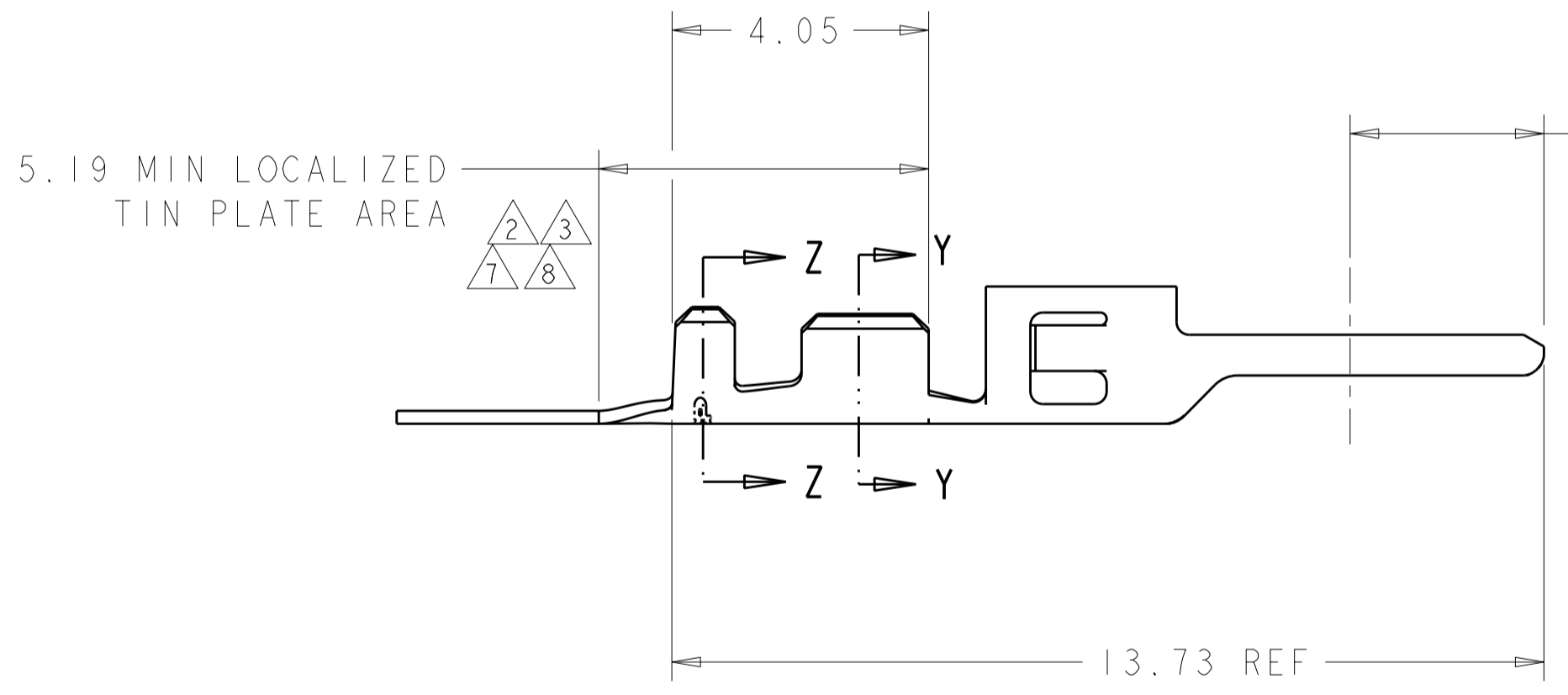


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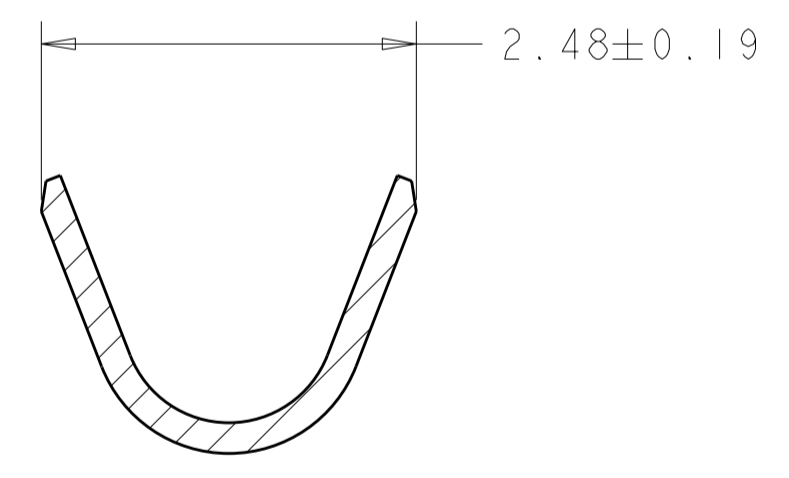
LOC	DIST	REVISIONS					
CM	00	P	LTR	DESCRIPTION	DATE	DWN	APVD
			D2	REVISED PER ECO-11-005027	15MAR2011	RK	HMR



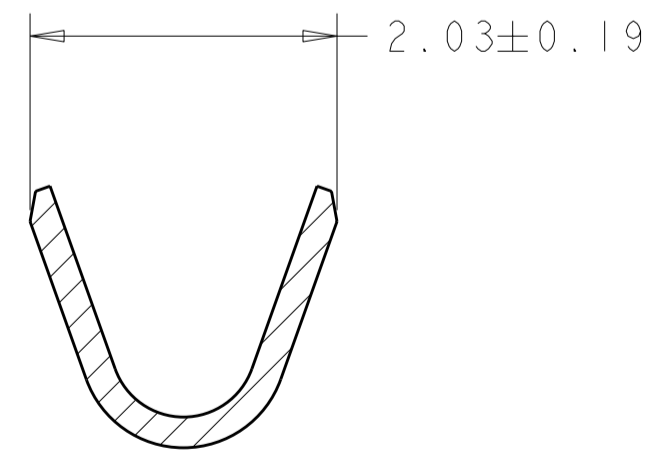
- 1 2.54 µm MIN BRIGHT TIN/LEAD ENTIRE STOCK OVER 1.27 µm MIN NICKEL ENTIRE STOCK.
- 2 0.38 µm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.54 µm MIN BRIGHT TIN/LEAD IN LOCALIZED TIN/LEAD PLATE AREA, BOTH OVER 1.27 µm MIN NICKEL ON ENTIRE STOCK.
- 3 0.76 µm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.54 µm MIN BRIGHT TIN/LEAD IN LOCALIZED TIN/LEAD PLATE AREA, BOTH OVER 1.27 µm MIN NICKEL ON ENTIRE STOCK.
- 4 WIRE RANGE 20-24 AWG.
- 5 INSULATION RANGE 0.89-1.52
- 6 2.54 µm MIN BRIGHT TIN ENTIRE STOCK OVER 1.27 µm MIN NICKEL ENTIRE STOCK.
- 7 0.38 µm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.54 µm MIN BRIGHT TIN IN LOCALIZED TIN PLATE AREA, BOTH OVER 1.27 µm MIN NICKEL ON ENTIRE STOCK.
- 8 0.76 µm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.54 µm MIN BRIGHT TIN IN LOCALIZED TIN PLATE AREA, BOTH OVER 1.27 µm MIN NICKEL ON ENTIRE STOCK.
- 9 NOTE DELETED.
- 10 TIN PLATING THICKNESS INSIDE WIRE AND INSULATION BARRELS TO BE 1.27 µm MIN.



3.00 MIN LOCALIZED GOLD PLATE AREA 2 3 7 8

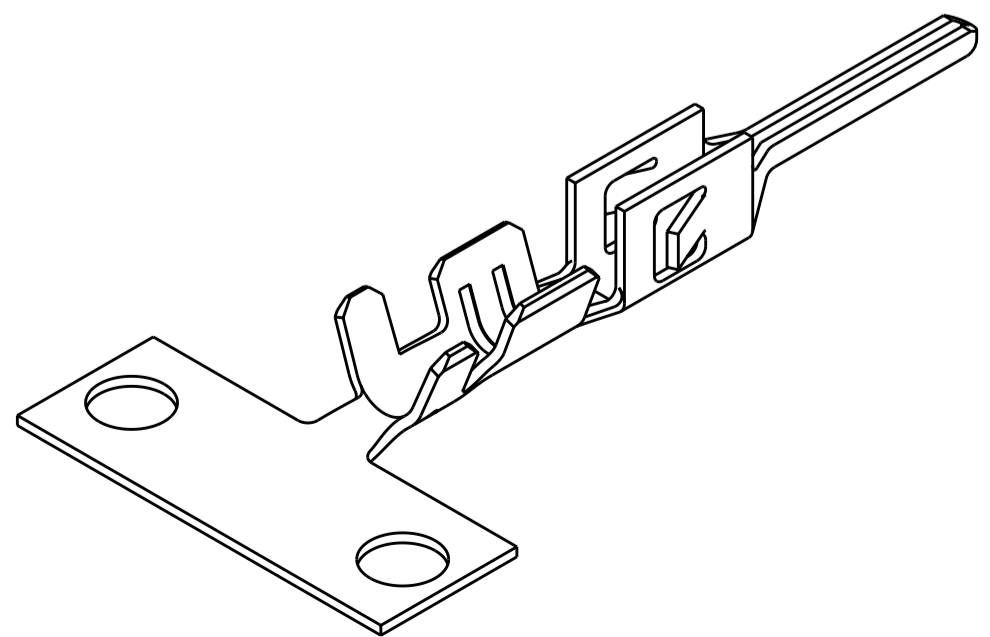


SECTION Z-Z
SCALE 20:1



SECTION Y-Y
SCALE 20:1

8	1-794608-2
7	1-794608-1
6	1-794608-0
3	794608-3
2	794608-2
1	794608-1
FINISH	PART NUMBER



THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DWN W J RUDY 29AUG2000	CHK W DAVIS 29AUG2000	APVD W DAVIS 29AUG2000	NAME
0 PLC ±	1 PLC ±	2 PLC ±0.13	3 PLC ±	4 PLC ±	PLUG CONTACT, CRIMP SNAP, 20-24 AWG, MICRO MATE-N-LOK(TM)
MATERIAL 0.20 THK BRASS		APPLICATION SPEC		WEIGHT	SIZE A200779
CUSTOMER DRAWING		SCALE 10:1		DRAWING NO C-794608	

STE TE Connectivity

RESTRICTED TO

SHEET 1 OF 1 REV D2